

Appl. No. 10/055,499  
Amdt. dated June 01, 2006  
Reply to Office action of March 01, 2006

**Amendments to the Claims:**

**Claims 1-280 (canceled)**

- 5 281. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:  
joining a die and a substrate, wherein said die has a top surface at a horizontal level; and  
after said joining said die and said substrate, depositing a gold bump over said  
10 horizontal level, ~~wherein said bump comprises gold.~~

282. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:  
joining multiple dies and a substrate;  
15 depositing an insulating layer over ~~a die~~ said multiple dies and said substrate,  
wherein said insulating layer comprises a porous structure; and  
separating said substrate into multiple portions.

283. (currently amended) A method for fabricating a circuitry ~~an electronic component~~,  
20 comprising:  
joining multiple dies ~~a die~~ and a substrate, wherein one of said multiple dies ~~die~~  
has a top surface at a horizontal level; and  
after said joining said multiple dies ~~die~~ and said substrate, depositing a passive  
device over said horizontal level; and  
25 separating said substrate into multiple portions.

284. (currently amended) A method for fabricating a circuitry ~~an electronic component~~,

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comprising:

joining multiple dies and a substrate, wherein one of said multiple dies has a top surface at a horizontal level;

- 5 providing a die having a top surface at a horizontal level; and  
waveguide over said horizontal level; and  
separating said substrate into multiple portions.

285. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:

- 10 providing a die having a top surface at a horizontal level; and  
depositing a micro electronic mechanical sensor (MEMS) over said horizontal level.

286. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:

- 15 depositing an insulating layer over a circuitry element;  
curing said insulating layer;  
grinding said insulating layer; and  
depositing a metal layer over said insulating layer.

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